CLAIMS

1. A method of treating a substrate, comprising:

delivering a first laser pulse having energy of 0.45 J/cm^2 and duration of 26 nsec to the substrate from a first laser;

delivering a second laser pulse having energy of 0.45 J/cm^2 and duration of 26 nsec to the substrate from a second laser;

after a first freeze period of 700 nsec, delivering a third laser pulse having energy of 0.45 J/cm^2 and duration of 26 nsec to the substrate from a third laser; and

after a second freeze period of 1,200 nsec, delivering a fourth laser pulse having energy of 0.26 J/cm^2 and duration of 26 nsec to the substrate from a fourth laser.

2. The method of claim 1, further comprising maintaining an ambient temperature of the substrate below 100°C.

3. The method of claim 1, further comprising repeating the delivery the first, second, third, and fourth laser pulses to the substrate.